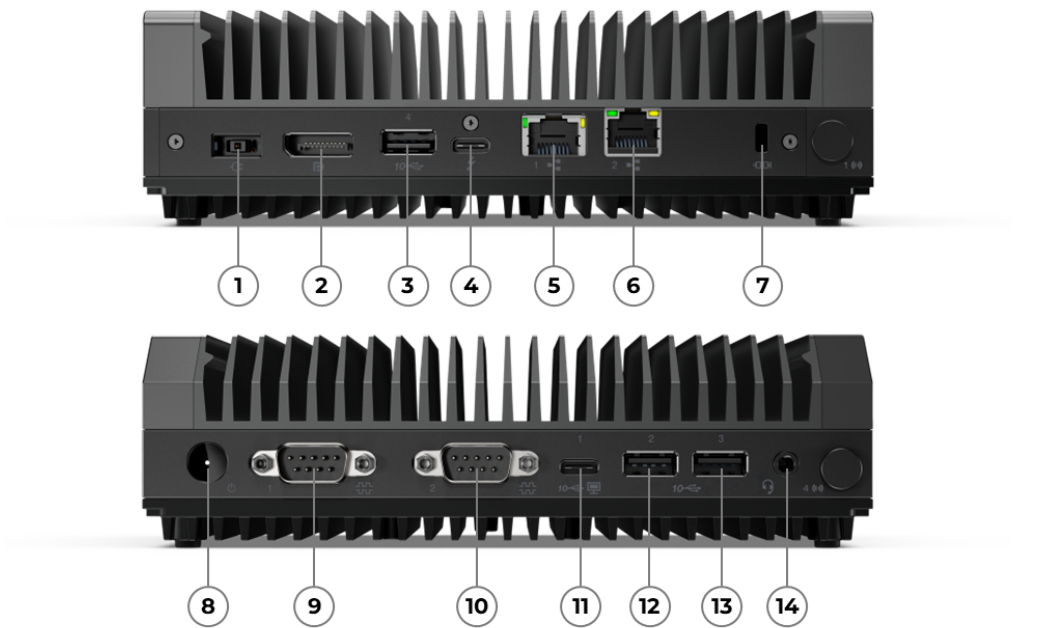


OVERVIEW



1. Power connector	8. Power button
2. HDMI (for Celeron, i3) / DisplayPort (for i5)	9. Serial
3. USB 3.2 Gen 2	10. Serial
4. Thunderbolt 4	11. USB-C 3.2 Gen 2
5. Ethernet (RJ-45)	12. USB 3.2 Gen 2
6. Ethernet (RJ-45)	13. USB 3.2 Gen 2
7. Kensington Security Slot	14. Headphone / microphone combo jack (3.5mm)

PERFORMANCE

Processor

Processor Family

Intel® Celeron® or 11th Generation Intel® Core™ i3 / i5 Processor

Processor**[1]

Processor Name	Cores	Threads	Base Frequency	Cache	Memory Support	Processor Graphics	Intel® vPro® Eligibility
Celeron® 6305E[2]	2	2	1.8GHz	4MB	DDR4-3200	Intel® UHD Graphics	-
Core i3-1115GRE[3]	2	4	1.7GHz	6MB	DDR4-3200	Intel® UHD Graphics	-
Core i5-1145G7E[4]	4	8	2.6GHz	8MB	DDR4-3200	Intel® Iris® Xe Graphics	Intel® vPro® Platform
Core i5-1145GRE[5]	4	8	1.1GHz	8MB	DDR4-3200	Intel® Iris® Xe Graphics	Intel® vPro® Platform

Notes:

[1] The Intel® Turbo Boost is disabled. The maximum Thermal Design Power (TDP) of microprocessor might be 12W, 15W, or 28W, which depends on different microprocessor series. The max frequency might not be obtainable at high work levels, so the microprocessor will adjust the frequency to obtain the maximum TDP allowed.

[2] The maximum Thermal Design Power (TDP) is 15W.

[3], [5] The maximum Thermal Design Power (TDP) is 12W.

[4] The maximum Thermal Design Power (TDP) is 28W.

Operating System

Operating System**

- Windows® 11 IoT Enterprise LTSC 2024
- Windows® 10 IoT Enterprise LTSC 2019[1]
- Windows® 10 IoT Enterprise LTSC 2021
- Ubuntu Core 20 64 Bit (kernel 5.13), Ubuntu (Server) 20.04 LTS 64 Bit (kernel 5.13)[2]
- Ubuntu Core 22 64 Bit (kernel 5.15), Ubuntu (Server) 22.04 LTS 64 Bit (kernel 5.15)[3]
- No preload operating system

Notes:

[1] For SKU operational temperature range: -20~60°C; For no Qualcomm® Snapdragon® X55 5G models

[2] For SKU operational temperature range: -20~60°C

[3] For SKU operational temperature range: 0~50°C; For no WWAN models

Graphics

Graphics**

Graphics	Type	Memory	Max Resolution	Connector	Key Features
Intel® UHD graphics	Integrated	Shared	3840x2160@30Hz(HDMI®), 3840x2160@60Hz(USB-C®), 3840x2160@60Hz(Thunderbolt™)	1x HDMI® 1.4b, 1x USB-C®, 1x Thunderbolt™	DirectX® 12
Intel® Iris® Xe Graphics	Integrated	Shared	3840x2160@60Hz(DP), 3840x2160@60Hz(USB-C®), 3840x2160@60Hz(Thunderbolt™)	1x DP 1.4a, 1x USB-C®, 1x Thunderbolt™	DirectX® 12

Monitor Support

Monitor Support

Supports up to 3 independent displays via onboard ports (Celeron®, i3 models supports HDMI®, USB-C®, and Thunderbolt™; i5 models supports DisplayPort™, USB-C®, and Thunderbolt™)

Chipset

Chipset

Intel® SoC (System on Chip) platform

Memory

Max Memory

Up to 16GB soldered memory, not upgradable

Memory Slots

Memory soldered to systemboard, no slots, dual-channel

Memory Type

DDR4-3200

Memory Protection^[1]

IB-ECC^[2]

Notes:

[1] IB-ECC needs to be enabled in BIOS.

[2] For SKU operational temperature range: -20-60°C

Storage

Max Storage Support^[1]

- Up to two drives, 2x M.2 SSD
- M.2 2280 SSD up to 2TB each
 - M.2 2230 SSD up to 1TB each
 - RAID 0/1 support

Storage Type***

Disk Type	Interface	Security
M.2 2230 SSD	PCIe® NVMe®, PCIe® 3.0	-
M.2 2230 SSD	PCIe® NVMe®, PCIe® 3.0	Opal
M.2 2280 SSD ^[2]	PCIe® NVMe®, PCIe® 4.0 x4	Opal 2.0
M.2 2280 SSD	PCIe® NVMe®, PCIe® 4.0 x4 Performance	Opal 2.0

RAID^[3]

RAID 0/1 support

Notes:

[1] M.2 2280 SSD is for SKU operational temperature range: 0-50°C

M.2 2230 SSD is for SKU operational temperature range: -20-60°C

[2] For SKU operational temperature range: 0-50°C, M.2 PCIe® Gen 4 SSD in a M.2 PCIe® Gen 3 slot runs at PCIe® Gen 3 speeds.

[3] RAID preset is available via special bid, limited to the models with Windows® 10 IoT Enterprise.

Power Supply

Power Supply**

Power	Type	Efficiency	Key Features	Dimensions
65W	Adapter	89%	100-240V	129 x 53 x 30 mm, 1800 mm cable
65W ^[1]	Adapter	88%	100-240V	108 x 46 x 29 mm, 1800 mm cable
No power adapter	-	-	-	-

Notes:

[1] For SKU operational temperature range: 0-50°C. The power adaptor is EOL

DESIGN

Input Device

Keyboard**

- Lenovo® Calliope Keyboard (USB connector), black

- Lenovo® Calliope Wireless Keyboard, black
- Lenovo® Traditional Keyboard (USB connector), black
- No keyboard

Mouse**

- Lenovo® Calliope Mouse (USB connector), black
- Lenovo® Fingerprint Mouse (USB connector), black (EOL on Jan, 2023)
- No mouse

Mechanical**Dimensions (WxDxH)^[1]**

Models	Dimensions
IO box	178 x 88 x 25.6 mm (7.01 x 3.46 x 1.00 inches)
ThinkEdge™ SE30	179 x 88 x 51.5 mm (7.05 x 3.46 x 2.03 inches)

Packaging Dimensions (WxDxH)**

- SE 30 (Mini package): 245 x 113 x 258 mm (9.65 x 4.45 x 10.16 inches)
- SE 30 (Standard package): 491 x 153 x 264 mm (19.33 x 6.02 x 10.39 inches)

Weight^[2]

Models	Weight
IO box	Around 0.499 kg (1.10 lbs)
ThinkEdge™ SE30	Around 1.02 kg (2.25 lbs)

Packaging Weight^[3]**

- SE30 (Mini package): Around 1.65 kg (3.63 lbs)
- SE30 (Standard package): Starting at 4.11 kg (9.06 lbs)

Case Color

Black

Expansion Slots

Three M.2 slots (one for WLAN, two for SSD)

IO Box^[4]

- ThinkEdge™ SE30 IO box: 2x serial (RS232 / RS422 / RS485) and 2x PoE (RJ-45) on front, 1x DIO (4DI / 4DO), USB-C® 3.2 Gen 1 (connect to SE30), and DC-in connector (9V - 36V) on rear^[5]
- No IO box

Mounting**

- VESA mount bracket kit with adapter holder, supports VESA mount 75mm and 100mm
- VESA mount bracket kit, supports VESA mount 75mm and 100mm
- DIN rail mount bracket kit
- Z hook
- None

Notes:

^[1] The system dimensions may vary depending on configurations.

^[2] The system weight is approximate and based on results in Lenovo® lab, which varies depending on the source of component, variance of the distribution of each component, and manufacturing process. It may not be the exact weight for each specific model.

^[3] The packaging weight is varies depending on the selected accessories.

^[4] For more details, please go to <https://pcsupport.lenovo.com>.

^[5] Please refer to the Hardware Manual-ThinkEdge™ SE30 IO BOX for PoE power delivery requirements: https://download.lenovo.com/consumer/iot/thinkedge_se30_hsm_en.pdf

CONNECTIVITY**Network****Ethernet****

- Gigabit Ethernet (Realtek® RTL8111KI) and 2.5 Gigabit Ethernet (Intel® I225-IT), 2x RJ-45, supports Wake-on-LAN^[1]

- Gigabit Ethernet (Realtek® RTL8111KI) and 2.5 Gigabit Ethernet (Intel® I225-LM), 2x RJ-45, supports Wake-on-LAN^[2]
- Gigabit Ethernet (Realtek® RTL8111KI) and 2.5 Gigabit Ethernet (Intel® I225-V), 2x RJ-45, supports Wake-on-LAN^[3]

WLAN + Bluetooth®^[4]**

- Intel® Wireless-AC 9260, Wi-Fi® 5, 802.11ac Dual Band 2x2 Wi-Fi® + Bluetooth® 5.1, Intel® vPro® technology support, M.2 card^[5]
- Intel® Wireless-AC 9260, Wi-Fi® 5, 802.11ac Dual Band 2x2 Wi-Fi® + Bluetooth® 5.1, M.2 card^[6]
- Intel® Wi-Fi® 6 AX201, 802.11ax 2x2 Wi-Fi® + Bluetooth® 5.1, Intel® vPro® technology support, M.2 card^[7]
- Intel® Wi-Fi® 6 AX201, 802.11ax 2x2 Wi-Fi® + Bluetooth® 5.1, M.2 card^[8]
- No WLAN and Bluetooth®

WWAN**

- Quectel EM160R-GL, 4G LTE CAT16
- SDX55, 5G Sub-6^[9]
- No support

Notes:

[1] For SKU operational temperature range: -20~60°C

[2] For SKU operational temperature range: 0~50°C with i5 processor

[3], [8] For SKU operational temperature range: 0~50°C with Celeron® processor

[4] Wi-Fi® operation (including Wi-Fi® 6, Wi-Fi® 6E, Wi-Fi® 7, etc.) is subject to the regulatory requirements of each country.

Bluetooth® may operate at a lower version than hardware design depending on the factors such as operating system, driver, etc.

[5] For SKU operational temperature range: -20~60°C with i5 processor.

[6] For SKU operational temperature range: -20~60°C with i3 processor

[7] For SKU operational temperature range: 0~50°C with i5 processor.

[9] The 5G WWAN card is EOL

Ports^[1]**Front Ports**

- 1x USB-C® 3.2 Gen 2 (support data transfer and display)
- 2x USB 3.2 Gen 2
- 1x headphone / microphone combo jack (3.5mm)
- 2x serial (RS232 / RS422 / RS485, BIOS selectable)

Optional Front Ports***

- 2x gigabit Ethernet (RJ-45) on SE30 IO box
- 2x serial (RS232 / RS422 / RS485, SDK selectable) on SE30 IO box

Rear Ports^[2]

- 1x Thunderbolt™ 4 / USB4® 40Gbps (support data transfer, Power Delivery 5V@3A and display)
- 1x HDMI® 1.4b (for Celeron®, i3 models)
- 1x DisplayPort™ 1.4a (for i5 models)
- 1x USB 3.2 Gen 2
- 1x power connector
- 2x Ethernet (RJ-45)

Optional Rear Ports***

- 1x USB-C® 3.2 Gen 1 on SE30 IO box, connect to SE30
- 1x DC-in 3pin Phoenix connector on SE30 IO box
- 1x DIO (4DI / 4DO) on SE30 IO box

Notes:

[1] The transfer speed of following ports will vary and, depending on many factors, such as the processing speed of the host device, file attributes and other factors related to system configuration and your operating environment, will be slower than theoretical speed.

USB 2.0: 480 Mbit/s;

USB 3.2 Gen 1 (SuperSpeed USB 5Gbps, formerly USB 3.0 / USB 3.1 Gen 1): 5 Gbit/s;

USB 3.2 Gen 2 (SuperSpeed USB 10Gbps, formerly USB 3.1 Gen 2): 10 Gbit/s;

USB4® 20Gbps / USB 3.2 Gen 2x2 (SuperSpeed USB 20Gbps): 20 Gbit/s;

USB4® 40Gbps (USB 40Gbps): 40 Gbit/s;

Thunderbolt™ 3/4: 40 Gbit/s.

Thunderbolt™ 5: 80 Gbit/s (bidirectional), up to 120 Gbit/s in bandwidth boost mode for video-intensive applications.

[2] If IO box gets power supply from ThinkEdge™ SE30, need to connect USB-C® (on IO box) with Thunderbolt™ 4 port (on SE30).

SECURITY & PRIVACY

Security

Security Chip

Discrete TPM 2.0, TCG certified

Physical Locks

Kensington® Security Slot™, 3 x 7 mm

Chassis Intrusion Switch

Chassis intrusion switch

BIOS Security

- Self-healing BIOS
- Self-healing BIOS (EC-based)

MANAGEABILITY

System Management

System Management^[1]

- Intel® vPro® with Intel® AMT 15
- Non-vPro®

Notes:

[1] Intel® vPro® platform require an eligible Intel® processor, a supported operating system, Intel® LAN and/or WLAN silicon, firmware enhancements, and other hardware and software necessary to deliver the manageability use cases, security features, system performance, and stability that define the platform. See [Intel® vPro® Platform](#) for details.

SERVICE

Warranty^[1]

Base Warranty**

- 1-year courier or carry-in service
- 1-year limited onsite service
- 3-year limited onsite service
- No base warranty

Notes:

[1] The warranty upgrades may be bundled with some models, please check the "Included upgrade" column in the specific model's configurations. For more service extensions, please go to <https://smartfind.lenovo.com/>. To learn more details of warranty policy, please access <https://support.lenovo.com/warrantylookup/warrantypolicy>.

ACCESSORIES

Bundled Accessories

Bundled Accessories

- DP to Dual DP (MST) dongle
- DP to Dual DP (SST) dongle
- DP to HDMI® dongle
- DP to VGA dongle
- USB-C® to DP dongle
- USB-C® to HDMI® dongle
- USB-C® to VGA dongle
- None

OPERATING REQUIREMENTS

Operating Environment^[1]

Temperature

- Operating: IEC60068-2-1 Test A: Cold, IEC 60068-2-2 Test B: Dry heat, -20°C (-4°F) to 60°C (140°F) with 0.7m/s air flow^[2]
- Operating: IEC60068-2-1 Test A: Cold, IEC 60068-2-2 Test B: Dry heat, 0°C (32°F) to 50°C (122°F) with 0.7m/s air flow^[3]
- Storage: IEC60068-2-1 Test A: Cold, IEC 60068-2-2 Test B: Dry heat, -40°C (-40°F) to 85°C (185°F)

Relative Humidity

- Relative humidity operating: IEC 60068-2-66 Damp heat, steady state 95%@40°C non-condensing
- Relative humidity storage: IEC 60068-2-66 Damp heat, steady state 90%@60°C

Shock Protection

IEC 60068-2-27, shock, operating, 30G / 11ms, half sine

Vibration Protection

IEC 60068-2-64, Vibration, Operating, 3Grms, random, 5 ~ 500Hz, 1hr/axis

Notes:

[1] The temperature spec is not applicable for hardware accessories.

[2] models include: 11NA, 11NB, 11NC, 11NJ

[3] models include: 11NK, 11NH

CERTIFICATIONS

Green Certifications

Green Certifications

- ErP Lot 6/26
- Low Halogen
- PCF
- REACH
- RoHS compliant
- TED (The ECO-declaration)
- WEEE

Other Certifications

EMC

- EMC CE / FCC Class B
- BSMI
- CCC

Safety

- UL(ETL)
- BSMI
- CB
- CCC

Mil-Spec Test

MIL-STD-810H military test passed

- Feature with ** means that only one option listed under the feature can be configured on selected models. Please refer to the model configuration for specific information.
- Feature with *** means that one or more options listed under the feature can be configured on selected models. Please refer to the model configuration for specific information.
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